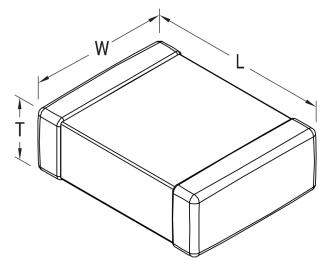


M123A12BPB301FZ

Aliases (C1808Z301F5GAL)

SMD Mil PRF123, Ceramic, 300 pF, 1%, 50 VDC, BP, SMD Chip, Ultra Stable, N/A, 1808



Click here for the 3D model.

| Chip Size 1808 L 4.572mm +/-0.381mm (0.18 in +/-0.015 in) |
|---|
| L 4.572mm +/-0.381mm (0.18 in +/-0.015 in) |
| |
| W 2.032mm +/-0.381mm (0.08 in +/-0.015 in) |
| T 1.651mm MAX (0.065 in MAX) |

| Packaging Specifications | |
|--------------------------|--------|
| Packaging | Waffle |
| Packaging Quantity | 25000 |

| General Informa | tion |
|-----------------|---|
| Series | SMD Mil PRF123 |
| Style | SMD Chip |
| Description | SMD Chip, Ultra Stable |
| RoHS | No |
| Prop 65 | A WARNING: Cancer and reproductive harm - http://www.p65warnings.ca.gov. |
| SCIP Number | 8780fdfd-a0b3-4664-b80c-18c07cfab0d1 |
| Termination | Tin |
| Failure Rate | N/A |
| AEC-Q200 | No |
| Shelf Life | 78 Weeks |
| MSL | 1 |

| Specifications | / |
|---|---------------------|
| Capacitance | 300 pF |
| Capacitance Tolerance | 1% |
| Voltage DC | 50 VDC |
| Dielectric Withstanding Voltage | 125 VDC |
| Temperature Range | -55/+125°C |
| Temperature Coefficient | BP |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 15%, 1MHz 1.0Vms |
| Dissipation Factor | 2.5% |
| Insulation Resistance | 100 GOhms |

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

单击下面可查看定价,库存,交付和生命周期等信息

>>KEMET(基美)